

Please see the attached Appendix for the changes made to claim 1.

Please enter new claims 9 and 10 as follows:

19. (New) A package board having a core board on each surface of which a plurality of conductor circuits are formed with an interlaminar resin insulating layer therebetween,
on an IC chip
wherein a plurality of soldering pads are formed ~~on the IC chip~~ mounted side surface, as well
~~as on an other side surface~~
~~as on the other side surface~~ to be connected to another board, so that said soldering pads on the other side surface are larger than those on said IC chip side surface of said package board, and

B²
a dummy pattern for improving the mechanical strength of the package board is formed between signal line conductor circuit patterns of an outmost layer formed on said IC chip mounted side surface of said core board.

30. (New) A package board having a core board on each surface of which a plurality of conductor circuits are formed with an interlaminar resin insulating layer therebetween,
on an IC chip
wherein a plurality of soldering pads are formed ~~on the IC chip~~ mounted side surface, as well
~~as on an other side surface~~
~~as on the other side surface~~ to be connected to another board, so that said soldering pads on the other side surface are larger than those on said IC chip side surface of said package board, and

a dummy pattern for improving the mechanical strength of the package board is formed between signal line conductor circuit patterns ~~on a core board~~ *on the core board* formed on said IC chip mounted side surface of said core board.